

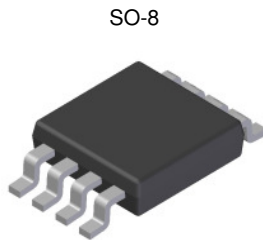
**60V N-CHANNEL ENHANCEMENT MODE MOSFET**
**Product Summary**

$V_{(BR)DSS}$	$R_{DS(on)}$	$I_D$ $T_A = +25^\circ C$
60V	66m $\Omega$ @ $V_{GS} = 10V$	5.0A
	97m $\Omega$ @ $V_{GS} = 4.5V$	4.1A

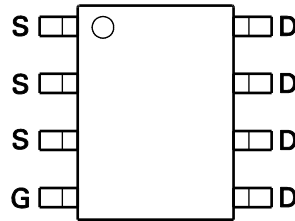
**Description and Applications**

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

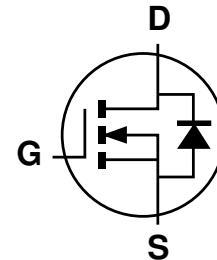
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions



Top View



Top View



Equivalent Circuit

**Features and Benefits**

- Low on-resistance
- Fast switching speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

**Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish – Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 <sup>Ⓔ</sup>
- Weight: 0.074 grams (Approximate)

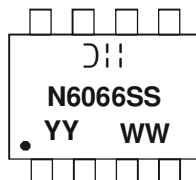
**Ordering Information** (Notes 4 & 5)

Part Number	Compliance	Case	Packaging
DMN6066SSS-13	Commercial	SO-8	2,500/Tape & Reel
DMN6066SSSQ-13	Automotive	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to [http://www.diodes.com/quality/product\\_grade\\_definitions/](http://www.diodes.com/quality/product_grade_definitions/).
  5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**

SO-8



$\text{D}|||$  = Manufacturer's Marking  
 N6066SS = Product Type Marking Code  
 YYWW = Date Code Marking  
 YY = Year (ex: 09 = 2009)  
 WW = Week (01 - 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

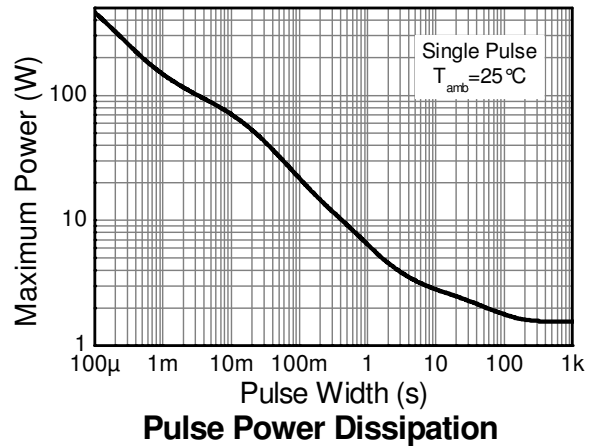
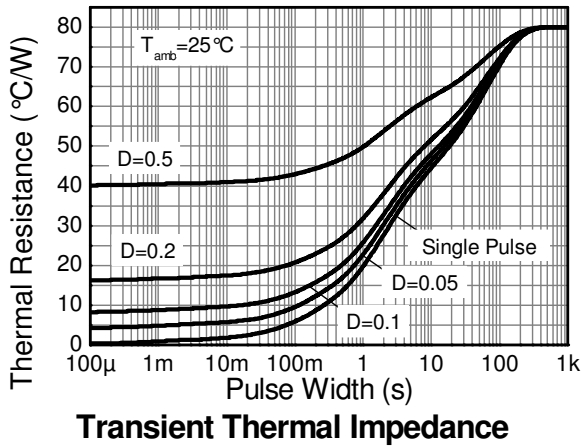
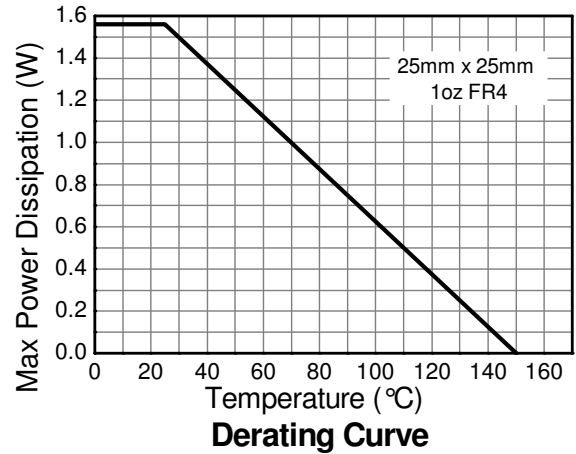
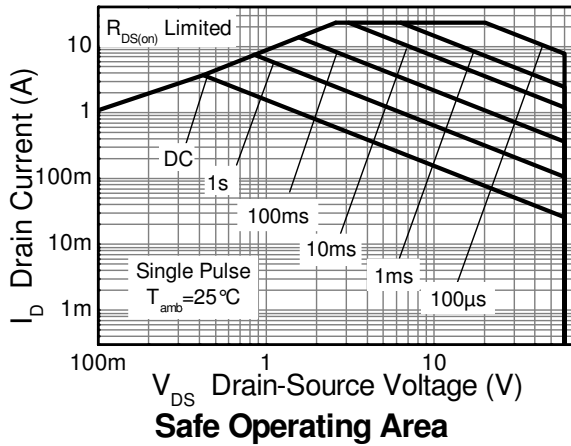
Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	60	V
Gate-Source Voltage	(Note 6)	V <sub>GS</sub>	±20	V
Single Pulsed Avalanche Energy		E <sub>AS</sub>	37.5	mJ
Single Pulsed Avalanche Current		I <sub>AS</sub>	5.0	A
Continuous Drain Current	V <sub>GS</sub> = 10V	(Note 8)	5.0	A
		T <sub>A</sub> = +70°C (Note 8)	4.0	
		(Note 7)	3.7	
Pulsed Drain Current	V <sub>GS</sub> = 10V	I <sub>DM</sub>	23	A
Continuous Source Current (Body diode)		I <sub>S</sub>	4.0	A
Pulsed Source Current (Body diode)		I <sub>SM</sub>	23	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 7)	P <sub>D</sub>	1.56	W
			12.5	
Linear Derating Factor	(Note 8)		2.81	mW/°C
			22.5	
Thermal Resistance, Junction to Ambient	(Note 7)	R <sub>θJA</sub>	80.0	°C/W
	(Note 8)		44.5	
Thermal Resistance, Junction to Lead	(Note 10)	R <sub>θJL</sub>	37.0	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

- Notes:
6. AEC-Q101 V<sub>GS</sub> maximum is ±16V.
  7. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
  8. Same as note (7), except the device is measured at t ≤ 10 sec.
  9. Same as note (7), except the device is pulsed with D= 0.02 and pulse width 300 μs. The pulse current is limited by the maximum junction temperature.
  10. Thermal resistance from junction to solder-point (at the end of the drain lead).
  11. UIS in production with L = 3.0mH, I<sub>AS</sub> = 5.0A, R<sub>G</sub> = 25Ω, V<sub>DD</sub>=50V, starting T<sub>J</sub> = +25°C.

**Thermal Characteristics**

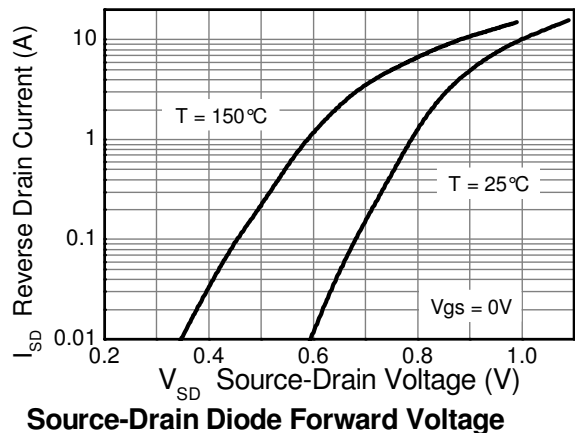
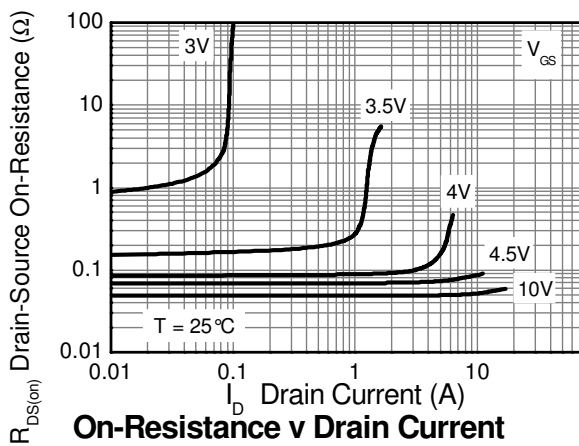
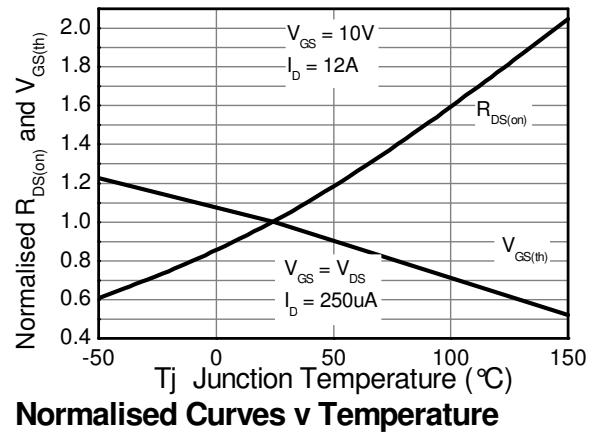
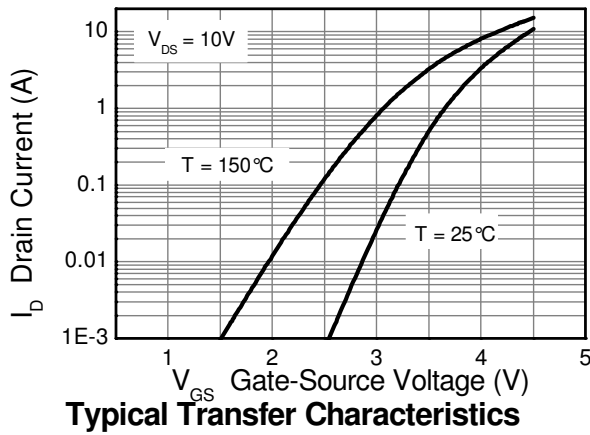
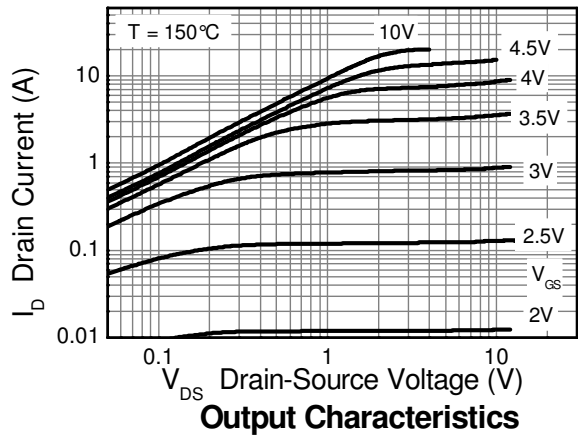
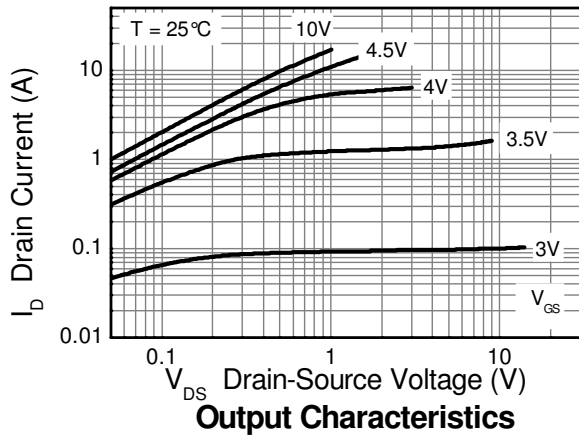


**Electrical Characteristics** (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

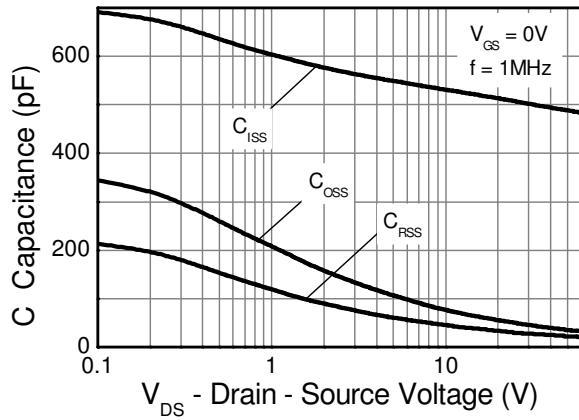
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	—	—	V	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	—	—	0.5	μA	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	—	3.0	V	I <sub>D</sub> = 250μA, V <sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 12)	R <sub>DS(on)</sub>	—	0.048	0.066	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.5A
			0.068	0.097		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A
Forward Transconductance (Notes 12 & 13)	g <sub>fs</sub>	—	19.2	—	S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 6A
Diode Forward Voltage (Note 12)	V <sub>SD</sub>	—	0.89	1.15	V	I <sub>S</sub> = 4.5A, V <sub>GS</sub> = 0V
Reverse Recovery Time (Note 13)	t <sub>rr</sub>	—	23	—	ns	I <sub>S</sub> = 2.4A, di/dt = 100A/μs
Reverse Recovery Charge (Note 13)	Q <sub>rr</sub>	—	19.7	—	nC	
<b>DYNAMIC CHARACTERISTICS (Note 13)</b>						
Input Capacitance	C <sub>iss</sub>	—	502	—	pF	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V f = 1MHz
Output Capacitance	C <sub>oss</sub>	—	45.7	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	27.1	—	pF	
Total Gate Charge (Note 14)	Q <sub>g</sub>	—	5.4	—	nC	V <sub>GS</sub> = 4.5V
Total Gate Charge (Note 14)	Q <sub>g</sub>	—	10.3	—	nC	V <sub>GS</sub> = 10V I <sub>D</sub> = 4.5A
Gate-Source Charge (Note 14)	Q <sub>gs</sub>	—	1.7	—	nC	
Gate-Drain Charge (Note 14)	Q <sub>gd</sub>	—	3.2	—	nC	
Turn-On Delay Time (Note 14)	t <sub>D(on)</sub>	—	2.7	—	ns	V <sub>DD</sub> = 30V, V <sub>GS</sub> = 10V I <sub>D</sub> = 1A, R <sub>G</sub> ≅ 6.0Ω
Turn-On Rise Time (Note 14)	t <sub>r</sub>	—	2.4	—	ns	
Turn-Off Delay Time (Note 14)	t <sub>D(off)</sub>	—	14.7	—	ns	
Turn-Off Fall Time (Note 14)	t <sub>f</sub>	—	5.4	—	ns	

- Notes:
12. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
  13. For design aid only, not subject to production testing.
  14. Switching characteristics are independent of operating junction temperatures.

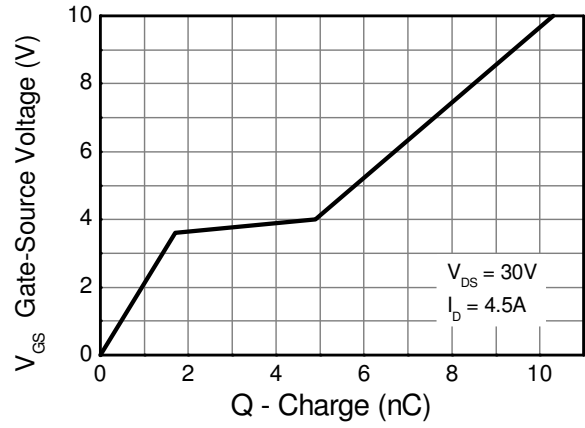
**Typical Characteristics**



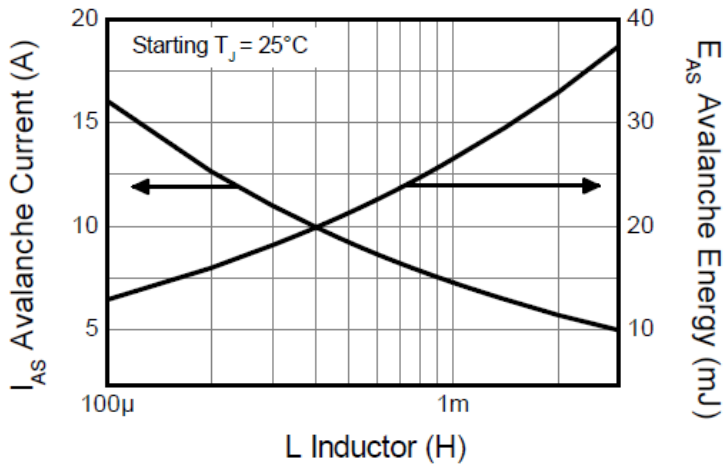
**Typical Characteristics** (continued)



**Capacitance v Drain-Source Voltage**

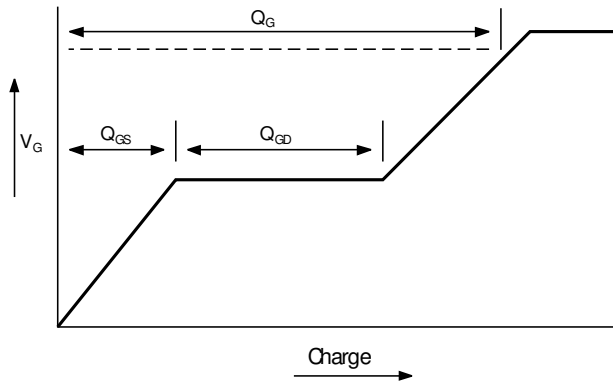


**Gate-Source Voltage v Gate Charge**

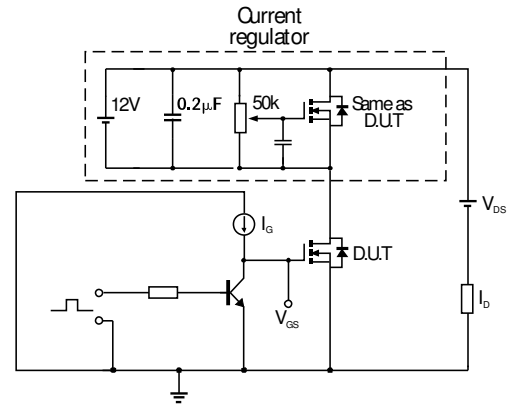


**Single-Pulsed Avalanche Rating**

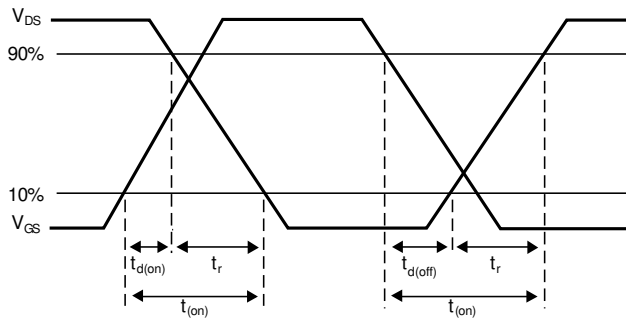
**Test Circuits**



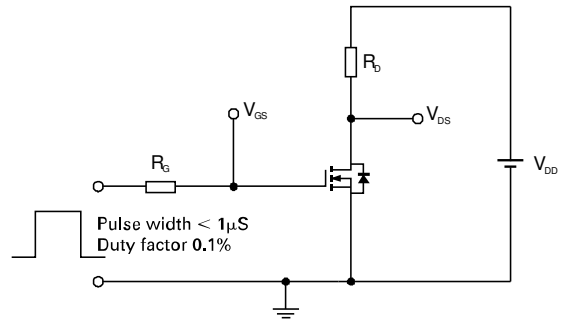
**Basic gate charge waveform**



**Gate charge test circuit**



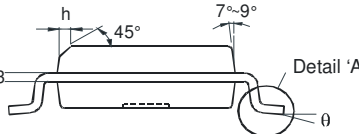
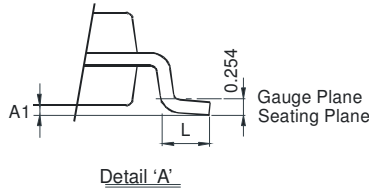
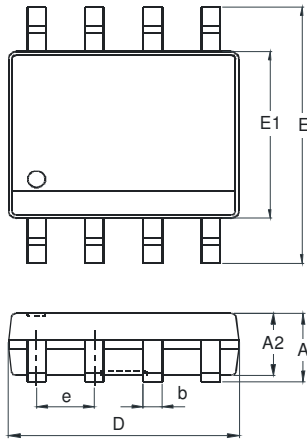
**Switching time waveforms**



**Switching time test circuit**

**Package Outline Dimensions**

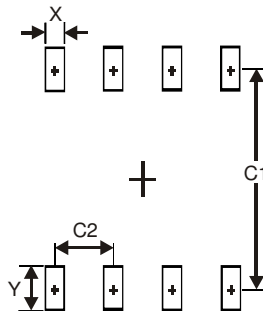
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
<b>All Dimensions in mm</b>		

**Suggested Pad Layout**

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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